

为您的产品保驾护航

PRODUCT DATASHEET

Gas Discharge Tubes

JTA25G/JTN25G

Description

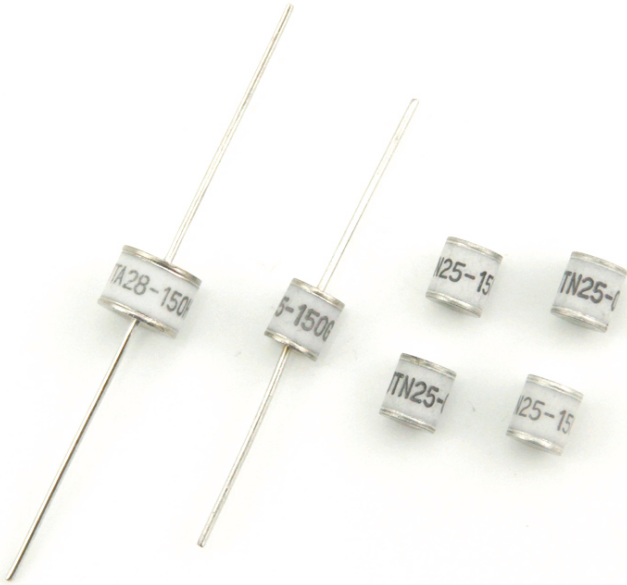
Gas discharge tubes (GDT) use noble gasses enclosed in ceramic tubes to provide an alternate circuit path for voltage spikes. The ceramic envelope and with nickel connectors allow for high loads and Ruilon offers products that function at 20KA, 40KA, 50KA, 60KA, 100KA & 150KA. The breakdown voltages of the devices have a wide range (up to 20% tolerance). Major applications are high frequency telecommunication lines, stations, security systems, HID and high quality Surge Protection Devices (SPD).

Features

- RoHS & HF compliant
- Size: 5.5mm*6.0mm
- DC Spark-over voltage: 75~800V
- Stable breakdown voltage.
- High insulation resistance.
- Low capacitance (<1pF)
- High holdover voltage.
- Large absorbing transient current capability.
- Low Capacitance
- Micro-Gap Design

Recommended Applications

- Cable Modem
- xDSL
- Set-Top Box
- Satellite and CATV equipment
- Power supplier
- Consumer electronics
- General telecom equipment



Product Identification

JT A 2 5 -075 G

G = Surge Rating

Blank=0.5kA, B=2kA, D=3kA,
G=5kA, H=10kA, K=20kA,
M=40kA, P=60kA

070 = DC Spark-over Voltage 75V

5 = 5mm Diameter

2 = 2 Electrode Device

A = Lead Configuration

A=Axial Leads
N=No Leads
S=Surface Mount
T=T-shaped Leads

JT = JDT Gas Discharge Tube

Gas Discharge Tubes - JTA25G/JTN25G Series

Part Number	DC Spark-over Voltage	Maximum Impulse Breakdown Voltage		Max. Impulse Discharge Current (8/20 μ s)		Impulse Life (10/1000 μ s)	Normal Alternating Discharge Current		DC Holdover Voltage	Minimum Insulation Resistance	Maximum Capacitance (1MHz)
	100V/S	100V/ μ S	1KV/ μ S	1 times	10 times	100 A	50Hz 1Sec	Single 9 Cycles			
	(V)	(V)	(V)	(KA)		Times	(A)				
JTA25-070G	70 \pm 20%	700	800	8	5	300	5	25	52	1	1
JTA25-075G	75 \pm 20%	700	800	8	5	300	5	25	52	1	1
JTA25-090G	90 \pm 20%	600	700	8	5	300	5	25	52	1	1
JTA25-150G	150 \pm 20%	600	700	8	5	300	5	25	52	1	1
JTA25-230G	230 \pm 20%	600	700	8	5	300	5	25	80	1	1
JTA25-250G	250 \pm 20%	600	700	8	5	300	5	25	80	1	1
JTA25-300G	300 \pm 20%	700	900	8	5	300	5	25	150	1	1
JTA25-350G	350 \pm 20%	700	900	8	5	300	5	25	150	1	1
JTA25-400G	400 \pm 20%	800	1000	8	5	300	5	25	150	1	1
JTA25-470G	470 \pm 20%	900	1100	8	5	300	5	25	150	1	1
JTA25-600G	600 \pm 20%	1300	1500	8	5	300	5	25	150	1	1
JTA25-800G	800 \pm 20%	1500	1700	8	5	300	5	25	150	1	1
JTN25-070G	70 \pm 20%	700	800	8	5	300	5	25	52	1	1
JTN25-075G	75 \pm 20%	700	800	8	5	300	5	25	52	1	1
JTN25-090G	90 \pm 20%	600	700	8	5	300	5	25	52	1	1
JTN25-150G	150 \pm 20%	600	700	8	5	300	5	25	52	1	1
JTN25-230G	230 \pm 20%	600	700	8	5	300	5	25	80	1	1
JTN25-250G	250 \pm 20%	600	700	8	5	300	5	25	80	1	1
JTN25-300G	300 \pm 20%	700	900	8	5	300	5	25	150	1	1
JTN25-350G	350 \pm 20%	700	900	8	5	300	5	25	150	1	1
JTN25-400G	400 \pm 20%	800	1000	8	5	300	5	25	150	1	1
JTN25-470G	470 \pm 20%	900	1100	8	5	300	5	25	150	1	1
JTN25-600G	600 \pm 20%	1300	1500	8	5	300	5	25	150	1	1
JTN25-800G	800 \pm 20%	1500	1700	8	5	300	5	25	150	1	1

DC Spark-over Voltage	DC Measuring Voltage
70-90V	50V
150-400V	100V
470-800V	250V

Soldering Parameters

Reflow Condition Pb-Free Assembly

Preheat

-Temperature Min($T_{s\ min}$)	150°C
-Temperature Max($T_{s\ max}$)	200°C
-Time($T_{s\ min}$ to $T_{s\ max}$)	60~180 seconds

Average Ramp-Up Rate (Liquidus Temp(T_L) to peak)	3°C/second max
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$T_{s(max)}$ to T_L - Ramp-up Rate	5°C/second max
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Reflow:

- Temperature (T_L) (Liquidus)	217°C
- Time (min to max) (t_s)	60~150 seconds

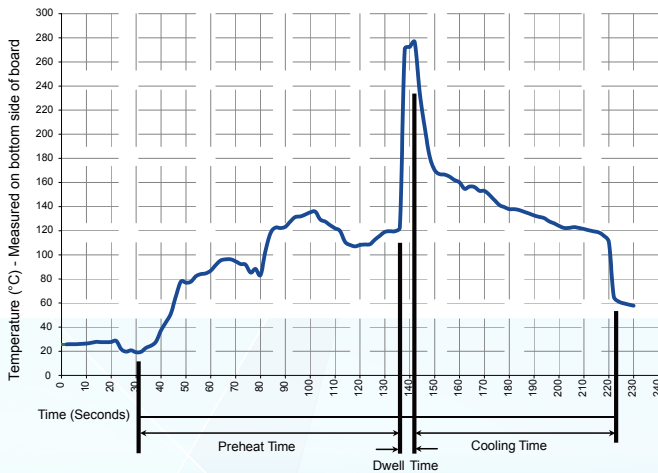
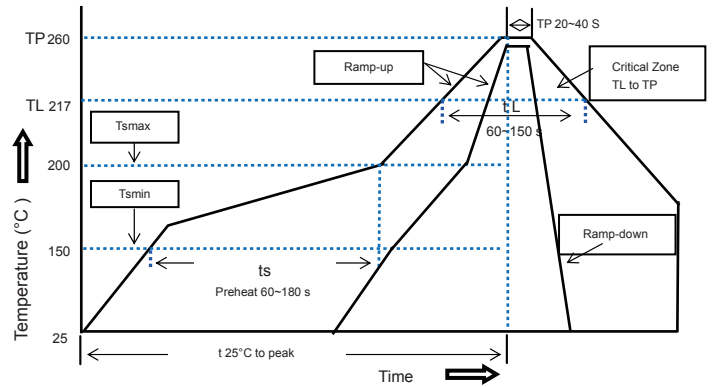
Peak Temperature(T_p)	260 ^{+0/-5} °C
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Time within 5°C of actual peak Temperature (t_p)	10~30 seconds
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Ramp-Down Rate	6°C/second max
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Time 25°C to Peak Temperature	8 minutes max
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Do not exceed	260°C
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Soldering Parameters

Recommended Process Parameters:

Wave Parameter	Lead-Free Recommendation
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Preheat:

(Depends on Flux Activation Temperature) (Typical Industry Recommendation)

Temperature Minimum:	100° C
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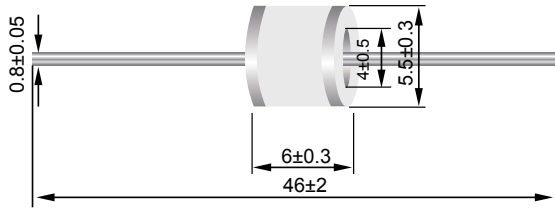
Temperature Maximum:	150° C
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Preheat Time:	60-180 seconds
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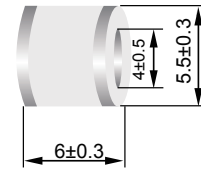
Solder Pot Temperature:	260° C Maximum
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Solder Dwell Time:	2-5 seconds
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Dimension unit:(mm)



(A)Series

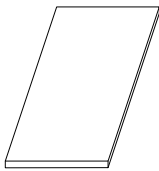


(N)Series

Packaging Taping

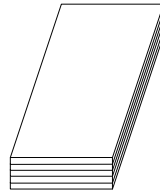
For " T " Type Axial Lead Items

Plastic Tray
(252×135×10mm)



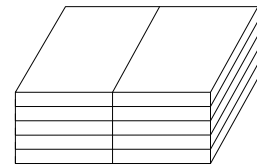
100 PCS/ Plastic Tray

Inner Box
(270×145×50mm)



500 PCS/ Box

Outside Box
(310×280×275mm)



5,000 PCS/ Carton

Core and ' S ' Type Items

